



PCN Tracking Number: PCN_FT_007

Issue Date: 2011-02-01

Product Change Notification

| | | |
|---|---|--------------------------------------|
| Product Part Number | FT2232HQ_Mini_Module, FT4232HQ_Mini_Module | Estimated implementation date |
| Description of Change | Modules have been redesigned to use the LQFP package, replacing the QFN package. | January 2011 |
| Reason for Change | To improve yield during the manufacturing process. | |
| Detailed Description | The mini modules PCB have been redesigned to accept the equivalent FT2232H and the FT4232H LQFP package rather than the existing QFN package. A ground test point has been added to aid debug. The PCB is now at Revision 1.1 | |
| Impact to Data sheet | Update to part numbers for clarity. | |
| Benefit of Change | The manufacturing yield increases. | |
| Markings to distinguish revised from: | Part numbers have change to drop the "Q". Part number FT2232HQ_Mini_Module will be replaced by FT2232H Mini Module Part number FT4232HQ_Mini_Module will be replaced by FT4232H Mini Module The silk screen of both the new PCBs is marked Rev 1.1 | |
| Sample Availability | January 2011 | |
| Risk Assessment, Fit Form and Function & reliability | Not applicable | |
| PDF Download | http://www.ftdichip.com/Support/Documents/ProductChangeNotifications/PCN_FT_007.pdf | |

Others:

Both the original and the updated mini module PCB/module are functionally identical. Only the FT2232H/FT4232H IC package used on the PCB has been changed from QFN to LQFP in order to increase manufacturing yield, plus the addition of the ground test probe point for ease of debug.

Mass production availability : December 2010